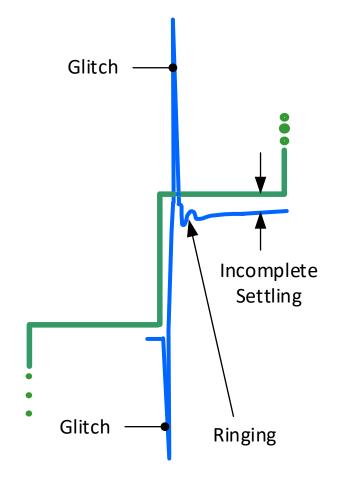
EE 505

Lecture 14

String DACs Current Steering DACs

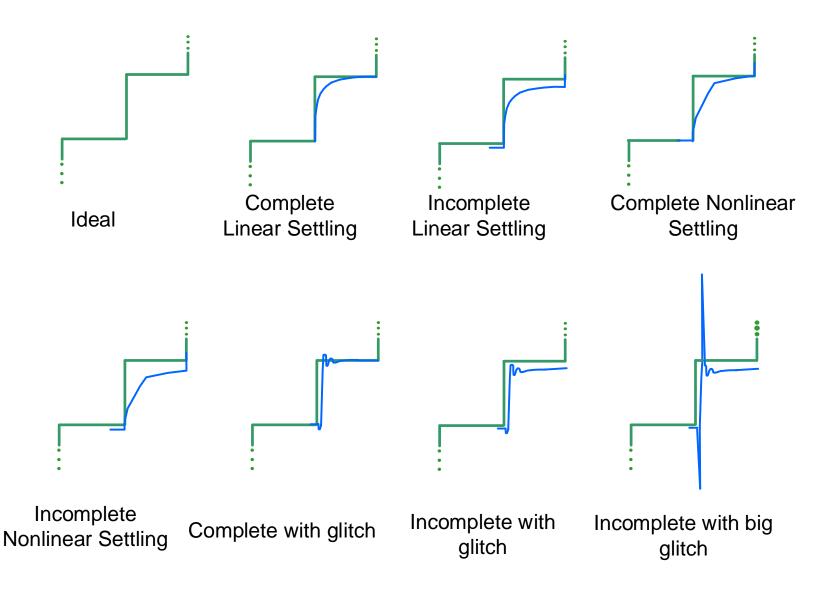
Review from Last Lecture

DAC Performance Issues and Concerns

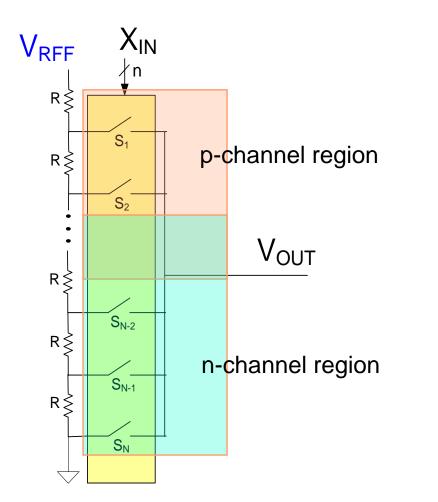


Review from Last Lecture

DAC Performance Issues and Concerns

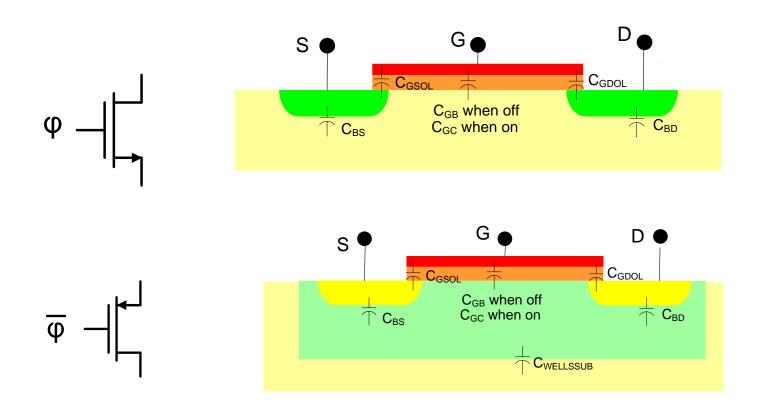


Review from Last Lecture Switch Assignment



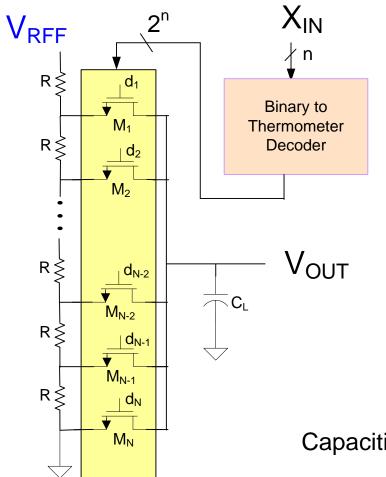
Challenges:

Switch Parasitics



- C_{BD} and C_{BS} can be significant and cause rise-fall times to be position dependent
- C_{GDOL} can cause "kickback" or feed-forward
- C_{GS} can slow turn-on and turn-off time of switch

Review from Last Lecture R-String DAC



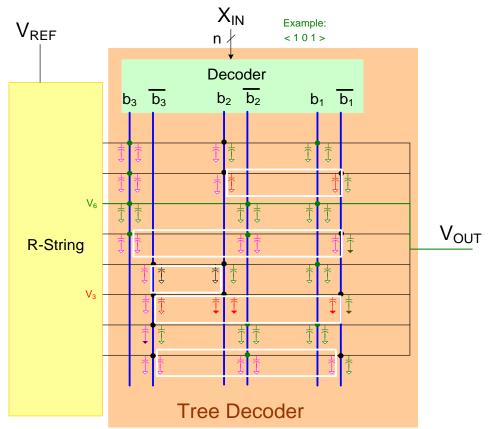
Capacitive loading due to switches

Review from Last Lecture

R-String DAC

Transition from <010> to <101>

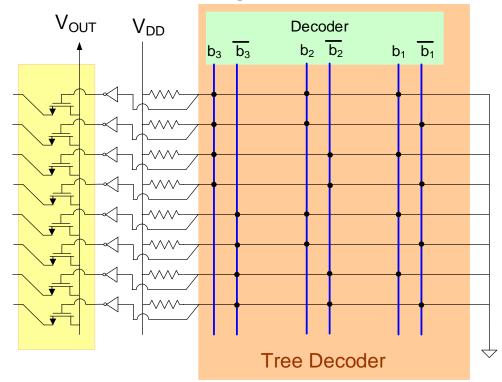
White boxes show capacitors dependent upon previous code <010>



Previous-Code Dependent Settling

- Assume all C's (except those on the R-string) were initially at 0V
- Red denotes V_3 , green denotes V_6 , black denotes 0V, Purple some other voltage
- Some capacitors may retain values from a previous input for many clock cycles for some inputs resulting I previous-previous dependence of even longer

Review from Last Lecture R-String DAC



Tree-Decoder in Digital Domain

Single transistor used at each marked intersection for PTLAND gates

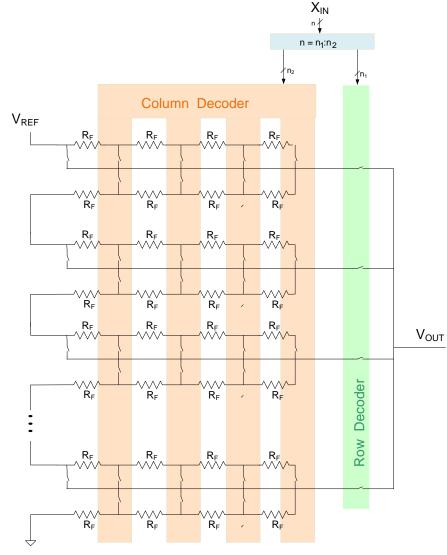
Dramatic reduction in capacitive loading at output

Do the resistors that form part of PTL dissipate any substantial power?

No because only one will be conducting for any DAC output

Will become more complicated if both p-channel and n-channel switches needed

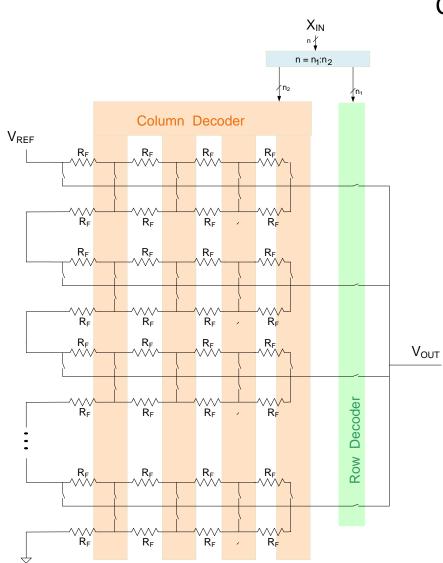
String DAC with Row-Column Decoder



- Dramatic reduction in decoder complexity
- Dramatic reduction of capacitive loading on output
- Changes decoder from a onedimensional to a two-dimensional solution (can be thought of as folding)
- Logic gates could be placed at each node to eliminate analog row decoder

Challenges (most were present in earlier structures too)

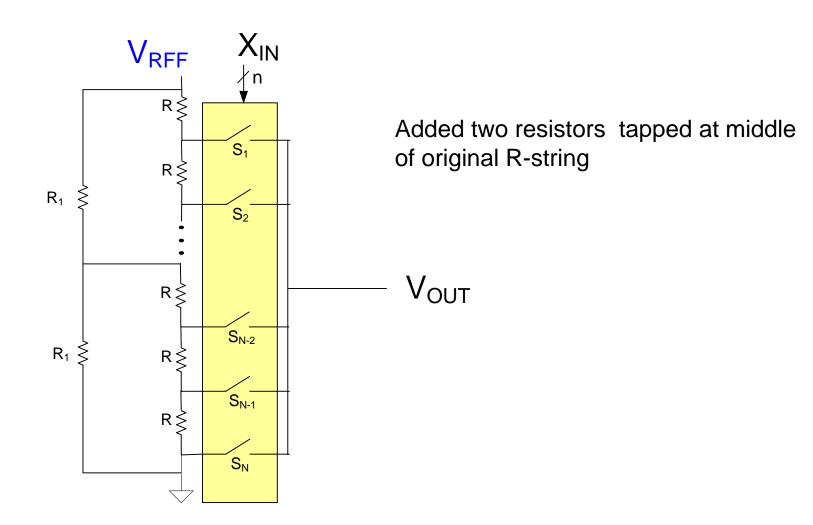
- Some previous code dependence
- INL large
- Difficult to cancel gradient effects in layout Switching sequencing can help a lot
- Switch impedances code dependent
- Settling times code dependent



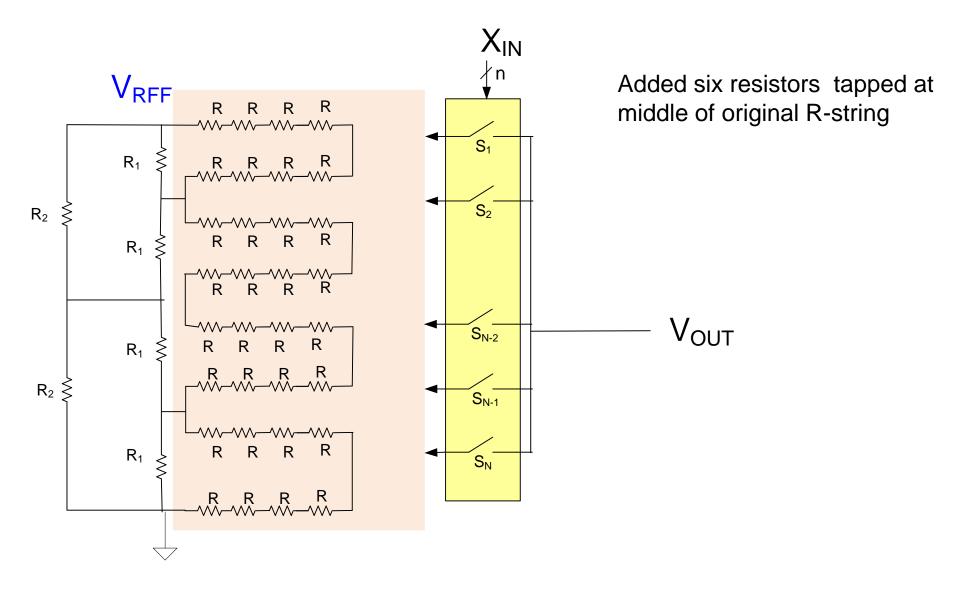
Can this concept be extended further?

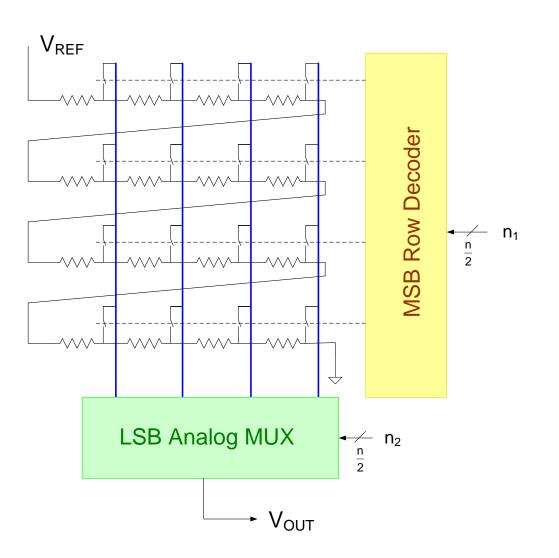
- Dramatic reduction in decoder complexity
- Dramatic reduction of capacitive loading on output
- Changes decoder from a onedimensional to a m-dimensional solution (folding)
- Logic gates could be placed at each node to eliminate analog row decoder

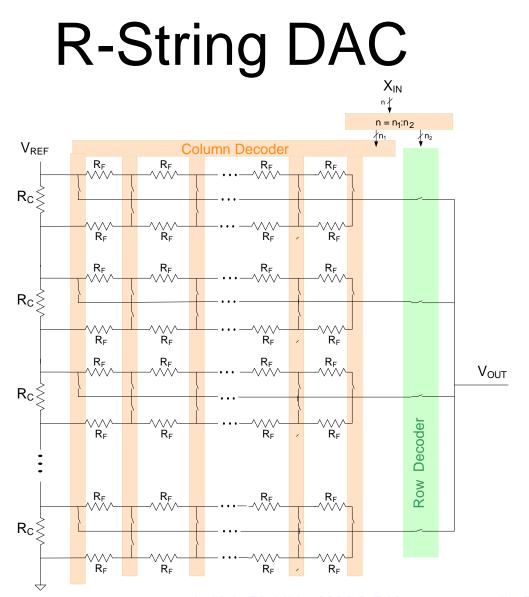
What about this parallel R-string?



What about this parallel R-string?



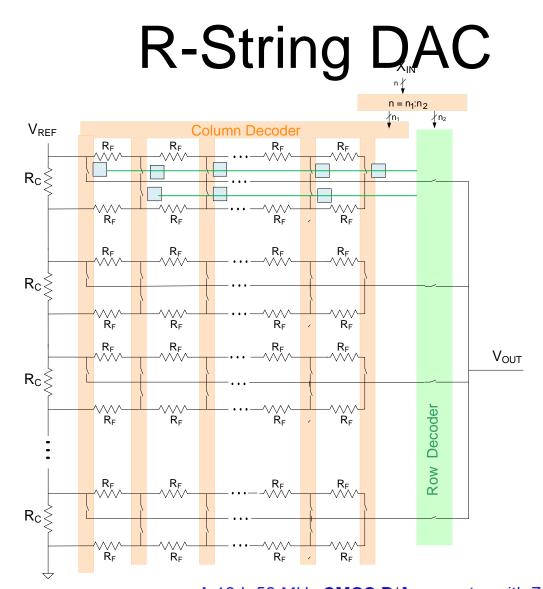




A 10-b 50-MHz **CMOS D**/A converter with 75- ω buffer

Note Dual Ladder is used !

MJM **Pelgrom** - Solid-State Circuits, IEEE Journal of, 1990 - ieeexplore.ieee.org Abstracf-A 10-b 50-MHz digital-to-analog (D/A) converter is pre-sented which is based on a dual-ladder resistor string. This approach allows the linearity requirements to be met without the need for selection or trimming. The D/A decoding scheme reduces the glitch energy, ... Cited by 109 Related articles All 3 versions Cite Save



A 10-b 50-MHz **CMOS D**/A converter with 75- ω buffer

Note Dual Ladder is used !

AND pixel sensor gate32x32 Matrix

MJM **Pelgrom** - Solid-State Circuits, IEEE Journal of, 1990 - ieeexplore.ieee.org Abstracf-A 10-b 50-MHz digital-to-analog (D/A) converter is pre-sented which is based on a dual-ladder resistor string. This approach allows the linearity requirements to be met without the need for selection or trimming. The D/A decoding scheme reduces the glitch energy, ... Cited by 109 Related articles All 3 versions Cite Save <u>A 10-b 50-MHz CMOS D/A converter with 75-Ω buffer</u> - <u>Get It@ISU</u> MJM **Pelgrom** - IEEE Journal of Solid-State Circuits, 1990 - ieeexplore.ieee.org Abstracf -A 10-b 50-MHz digital-to-analog (D/A) converter is pre- sented which is based on a dual-ladder resistor string. This approach allows the linearity requirements to be met without the need for selection or trimming. The D/A ... <u>Cited by 45</u> - <u>Related articles</u> - <u>Web Search</u> - <u>All 2 versions</u>

Cited by 51 (4/5/10) Cited by 109 (4/5/16) Cited by 94 (4/6/14) Cited by 133 (3/8/21) A 10-b 50-MHz CMOS D/A Converter with 75- Ω Buffer

MARCEL J. M. PELGROM, MEMBER, IEEE

Abstract —A 10-b 50-MHz digital-to-analog (D/A) converter is presented which is based on a dual-ladder resistor string. This approach allows the linearity requirements to be met without the need for selection or trimming. The D/A decoding scheme reduces the glitch energy, and signal-dependent switch signals reduce high-frequency distortion. The output buffer allows driving 1 V_{pp} to 75 Ω . The chip consumes 65 mW at maximum clock frequency and a full-swing output signal. The device is processed in a standard 1.6- μ m CMOS process with a single 5-V supply voltage. Current-based circuits dump the complementary part of the signal current to ground: the power supply current is thereby twice the average signal current. If a two-sided terminated transmission line has to be fed by the highimpedance output of the current cell D/A converter, the current should be doubled to obtain the required output swing. In this case, the power supply current is four times the average signal current. A triple video D/A converter

Current-based circuits dump the complementary part of the signal current to ground: the power supply current is thereby twice the average signal current. If a two-sided terminated transmission line has to be fed by the highimpedance output of the current cell D/A converter, the current should be doubled to obtain the required output swing. In this case, the power supply current is four times the average signal current. A triple video D/A converter intended for supplying 1 V_{pp} to 75 Ω will consequently require 80-mA power supply current.

This paper proposes a trimless 10-b 50-MHz D/A converter based on resistor strings. This D/A converter is well suited to be used together with nearly all reported A/D converters for high speed, as these also use resistor strings to obtain the reference for the comparators. The design improves on the standard single-resistor-string approach by using a dual-ladder architecture [3] in a matrix formation [4], [5]. Several measures have been taken in the ladder to reduce the distortion. The decoding aims at minimizing the number of transistors that switch. The on-chip output buffer allows driving 1 V_{pp} to 75 Ω . The inherent voltage output allows driving a two-sided terminated transmission line with a better power efficiency than a current cell D/A converter.

Section II presents the design considerations and chip architecture and Section III shows some measurements on the device. The work is summarized in Section IV.

II. THE CHIP DESIGN

A. The Ladder Structure

The voltage dependence and the mutual matching of large-area polysilicon resistors allow the design of a converter with high integral and differential linearity. Basically, the variation in the polysilicon resistance value is determined by its geometry variations: the length and width variations result in local mismatches and the thickness variation gives gradients. Equally sized MOS gates suffer in addition to charge variations in the threshold voltage. However, the design of the D/A converter with a single 1024-tap resistor ladder and sufficiently fast output settling requires tap resistors in the order of $6-10 \ \Omega$. The size of such resistors in conventional polysilicon technology is such that accurate resistor matching and consequently linearity become a problem.

The solution to this problem is the combination of a dual ladder [3] with a matrix organization Randy Geiger Fig. 1 shows the ladder structure. The coarse ladder consists of two ladders each with 16 large-area resistors of 250 Ω which are connected anti-parallel to eliminate the firstorder resistivity gradient. The coarse ladder determines 16 accurate tap voltages and is responsible for the integral linearity. A 1024-resistor fine ladder is arranged in a 32-by-32 matrix, where every 64th tap is connected to the coarse-ladder taps. This arrangement allows the fineladder tap resistance to be increased to 75 Ω without loss of speed. The effect of wiring resistances has to be related to the 75- Ω tap resistors and can therefore be neglected. There are only currents in the connections between the ladders in the case of ladder inequalities: this reduces the effect of contact resistance variance. The current density in the polysilicon is kept constant to avoid field-dependent nonlinearities. The coarse ladder is designed with polysilicon resistors in order to avoid voltage dependence of diffused resistors. The fine ladder is designed either in polysilicon or diffusion, depending on secondary effects in the process implementation.

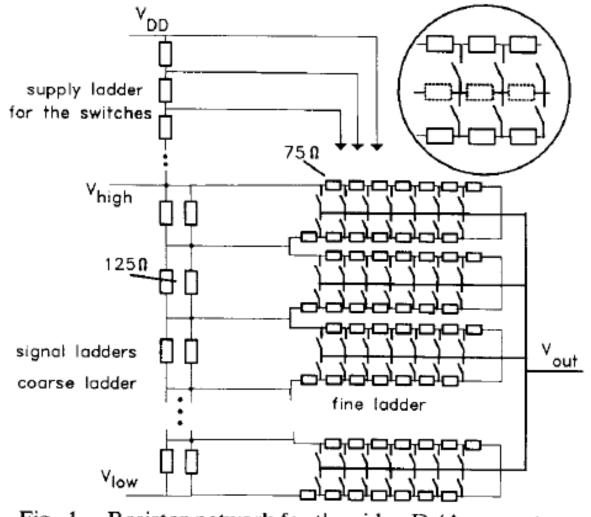


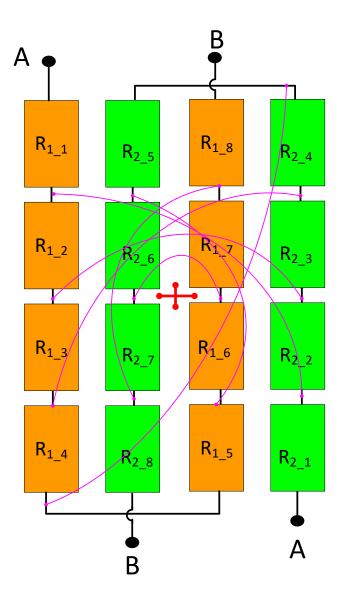
Fig. 1. Resistor network for the video D/A converter.

In a basic ladder design consisting of one string of 1024 resistors, the output impedance of the structure varies with the selected position on the ladder and therefore with the applied code. The varying output impedance in combination with the load capacitance results in unequal output charging time and consequently signal distortion. of high-frequency output signals. This source of varying impedance has been eliminated by means of a resistive output rail. The insert in Fig. 1 shows a part of two rows of the matrix. Small resistors are placed in the output rail which connects the switches together. These resistors can be chosen in such a way that any path from the beginning of the resistor row to the end of the output rail shows the same impedance, independent of the chosen switch. This eliminates position-dependent charging of the output rail

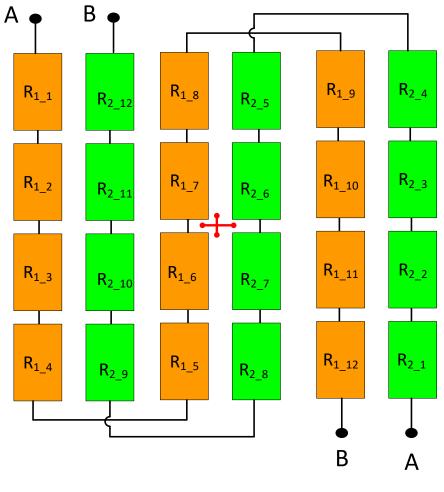
and therefore reduces the odd harmonics. In this design, partial cancellation was achieved by placing a unity resistor at the appropriate positions in the output rail. The use of unity resistors keeps the layout simple and does not require additional chip area.

The second source of the varying output impedance is the switch transistor. Usually its on-state gate voltage equals the positive power supply; the voltage on its source terminal, however, is position dependent. The turn-on voltage doubles from one end of the ladder to the other. In this design an additional supply ladder is placed on top of the signal ladders to keep the turn-on voltage of the switches more constant. Effectively the turn-on voltage of each switch transistor is made equal to the lowest turn-on voltage of a basic ladder D/A structure. Therefore there are no additional power supply constraints. For an easy implementation, the switches along each output rail have a common supply line. The variation in turn-on voltage is thereby reduced by a factor of 16. The upper group of switches is fed from the power supply while each lower group is fed with a voltage lowered by one-sixteenth of the maximum signal swing. An additional advantage of this compensation is that the impedance of the switch can be in the order of the total ladder resistance: the switches reduce in width and consequently the clock feedthrough is also reduced.

Common-Centroid Anti-Parallel Ladder Layout



Common-Centroid Anti-Parallel Ladder Layout



Interconnects Not Shown

B. The Digital Decoder

The core of the D/A converter is formed by the 32-by-32 fine-resistor matrix. A switch and a two-input AND gate¹ are connected to each fine resistor to form a basic cell. Two rows of 32 cells each are arranged around one output rail to form one of the 16 sections of the 10-b D/A converter (see Fig. 2). In operation one of the tap voltages of the fine ladder is switched to one of the 16 output rails of the matrix and subsequently to the input of the buffer. In order to select the proper switch, the 10-b digital input word is split in two 5-b words which are decoded by two sets of 5-to-32 decoders, as shown in Fig. 2. The 5-to-32 decoding is performed in two steps: a predecoder converts into ten lines that control 32 threeinput NOR gates of which one gate is activated. In this way minimum capacitive load is driven and maximum speed is achieved. The two decoders are placed on two sides of the matrix. The two sets of 32 decoded lines are latched by the main clock before running horizontally and verti-

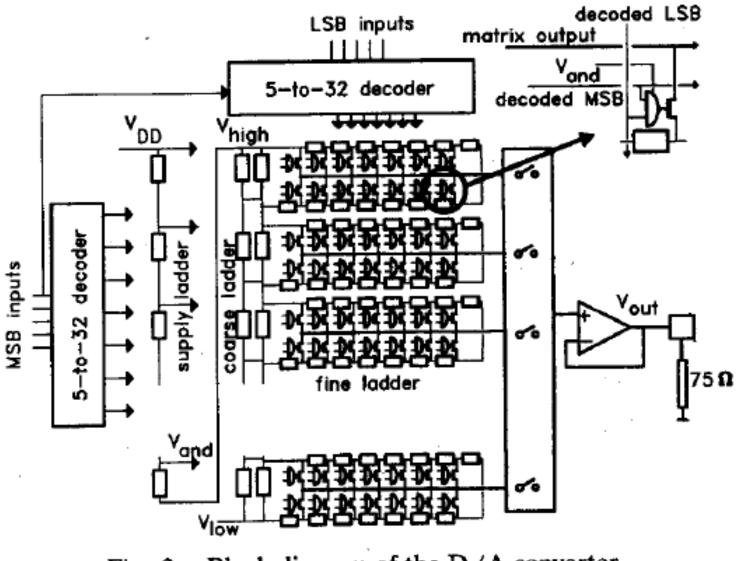
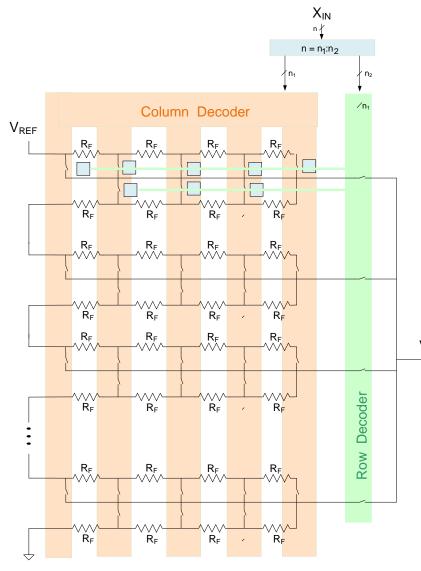


Fig. 2. Block diagram of the D/A converter.

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String DAC with Row-Column Decoder

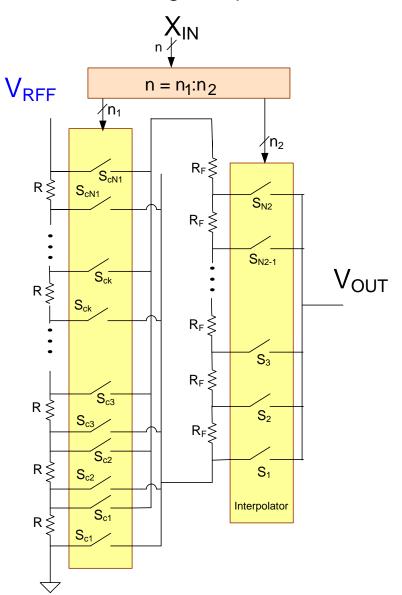


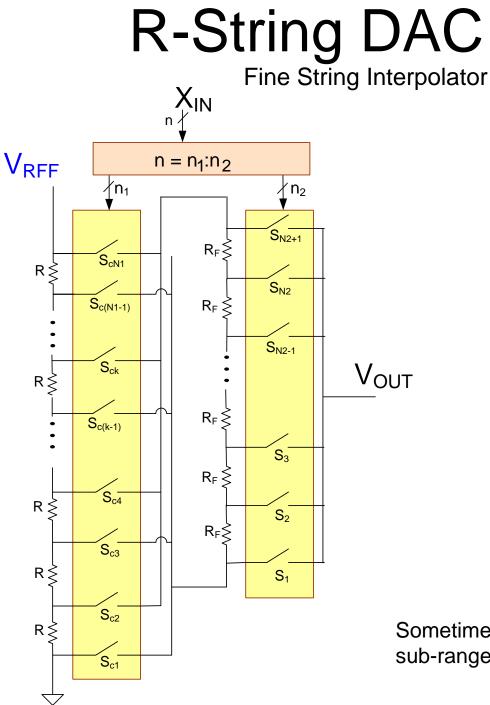
- Dramatic reduction in decoder complexity
- Dramatic reduction of capacitive loading on output
- Changes decoder from a onedimensional to a two-dimensional solution (can be thought of as folding)
- Logic gates could be placed at each node to eliminate analog row decoder
- $\mathsf{V}_{\mathsf{OUT}}$

Challenges (most were present in earlier structures too)

- Some previous code dependence
- INL large
- Difficult to cancel gradient effects in layout Switching sequencing can help a lot
- Switch impedances code dependent
- Settling times code dependent

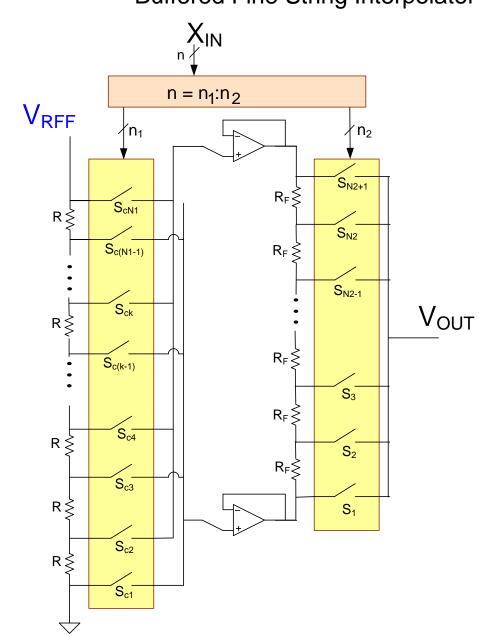
Fine String Interpolator

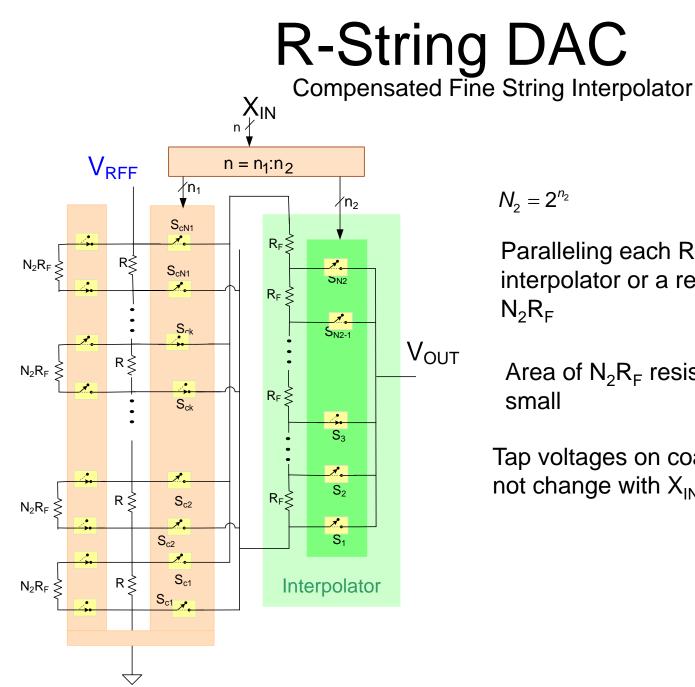




Sometimes termed sub-divider, sub-range or dual-string DAC

R-String DAC Buffered Fine String Interpolator



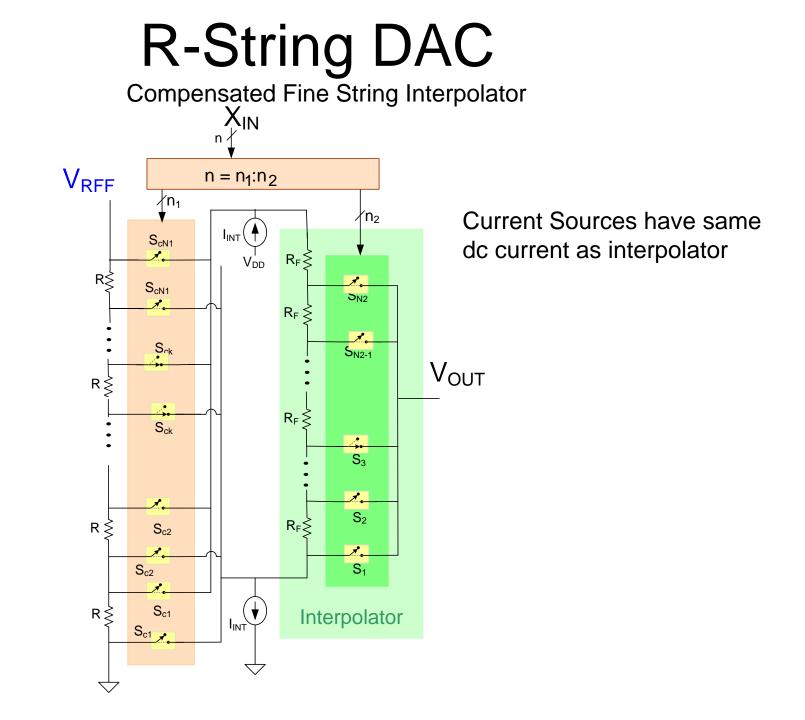


 $N_2 = 2^{n_2}$

Paralleling each R will be either the interpolator or a resistor of value N_2R_F

Area of N_2R_F resistors may be very small

Tap voltages on coarse R-string should not change with X_{IN}





Stay Safe and Stay Healthy !

End of Lecture 14